

PROCESS FOR PRODUCING A PRINTED WIRING BOARD-FORMING SHEET
AND MULTI-LAYERED PRINTED WIRING BOARD

CROSS-REFERENCE TO RELATED APPLICATIONS

10/26/06 *eye*
This application is a division of U.S. Patent Application No. 09/744,424 filed January 24, 2001, *now abandoned* which is a national phase filing of PCT/JP00/02879 filed May 1, 2000.

BACKGROUND OF THE INVENTION

FIELD OF THE INVENTION

The present invention relates to a printed wiring board-forming sheet, a via hole-forming method, a process for producing a resin sheet having a filled via hole, a device for forming the via hole, a TAB (tape automated bonding) tape, CSP (chip size package), BGA (ball grid array), FPC (flexible printed circuit), a so-called multi-layer board using a rigid substrate such as glass epoxy, a multi-layer printed wiring board capable of being produced by the use of a punching press, and a process for producing the same.

DESCRIPTION OF RELATED ART

A conventional process for producing a resin sheet having a filled via hole is described below with reference to Fig. 25.

In the first place, a die having an upper part 112 provided with a punch 110 and a lower part 116 (sometimes referred to as a "base") having a die hole 114 formed at the position corresponding to the punch